

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Hans-Jurgen Albrecht, et al.	)	: Examiner: S.J. Cohen
Application No.: 10/554,274	)	: Group Art No.: 1793
Filed: September 13, 2006	)	: Confirmation No.: 3094
For: SOLDERING MATERIAL BASED ON Sn	)	:
Ag AND Cu	)	: April 27, 2010

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

In response to the Office Action mailed January 27, 2010, kindly amend the subject application as follows.

Amendments to the claims begin on page 2 of this paper.

Remarks begin on page 4 of this paper.